

Title (en)

METHOD FOR FORMING MICROWIRES AND/OR NANOWIRES

Title (de)

VERFAHREN ZUR BILDUNG VON MIKRODRÄHTEN UND/ODER NANODRÄHTEN

Title (fr)

PROCEDE DE REALISATION DE MICROFILS ET/OU DE NANOFILS

Publication

**EP 2095407 A1 20090902 (FR)**

Application

**EP 07857946 A 20071220**

Priority

- EP 2007064325 W 20071220
- FR 0655822 A 20061221

Abstract (en)

[origin: WO2008074862A1] The invention relates to a method for forming a wire (112) in a layer (102) based on an amorphous or monocrystalline material, comprising the following steps in which: two trenches (110) are formed in the layer so as to extend through one face (101) thereof, said trenches being separated from one another by a portion of the layer and formed by etching the layer on which an etching mask (108) has been disposed; and the layer is annealed in a hydrogenated atmosphere, the etching mask being retained on the layer during said annealing step. The depths and widths of the sections of the two trenches and the width of a section of the above-mentioned portion of the layer are such that the annealing process removes part of said portion of the layer, so that the two trenches then form a single trench (114) in which a remaining part of said portion forms the wire.

IPC 8 full level

**H01L 21/336** (2006.01); **B81C 1/00** (2006.01); **H01L 29/786** (2006.01)

CPC (source: EP US)

**B82Y 10/00** (2013.01 - EP US); **H01L 29/42392** (2013.01 - EP US); **H01L 29/66795** (2013.01 - EP US); **H01L 29/7853** (2013.01 - EP US); **H01L 29/7854** (2013.01 - EP US); **Y10S 977/938** (2013.01 - EP)

Citation (search report)

See references of WO 2008074862A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

**FR 2910456 A1 20080627; FR 2910456 B1 20180209;** EP 2095407 A1 20090902; US 2010047973 A1 20100225; US 7985632 B2 20110726; WO 2008074862 A1 20080626

DOCDB simple family (application)

**FR 0655822 A 20061221;** EP 07857946 A 20071220; EP 2007064325 W 20071220; US 52038507 A 20071220